

LISTING OF THE CLAIMS

Please amend the claims as follows:

Claim 1 (Previously Presented): An elastic conductive resin composition, comprising an elastic resin and an acicular conductive filler, said filler having an aspect ratio of 20 to 50 ~~5-200~~ and comprising a surface layer of gold, silver, nickel, or copper, wherein the diameter of the filler is 0.5 to 2.0 μm .

Claims 2-25 (Canceled).

Claim 26 (New): The elastic conductive resin composition of claim 1, wherein the aspect ratio of the acicular conductive filler is 20-40.

Claim 27 (New): The elastic conductive resin composition of claim 1, wherein the acicular conductive filler comprises a whisker as a core material.

Claim 28 (New): The elastic conductive resin composition of claim 27, wherein the whisker is a high-polymer whisker.

Claim 29 (New): The elastic conductive resin composition of claim 1, wherein the elastic resin is a silicone resin comprising both an ultraviolet-curing property and a humidity curing property.

Claim 30 (New): The elastic conductive resin composition of claim 1, wherein the aspect ratio of the acicular conductive filler is from 20-50.

Claim 31 (New): A method of making an electronic device,
wherein the electronic device comprises
an electric part comprising
at least one first electrode,
a substrate comprising at least one second electrode, and
at least one bump formed on the at least one first electrode,
comprising
connecting the at least one first electrode to the at least one second electrode
via the at least one bump to from the electronic device,
wherein the at least one bump comprises the elastic conductive resin
composition of claim 1.

Claim 32 (New): The method of claim 31,
wherein the at least one bump is shaped such that the bump gradually thins to a tip,
and
wherein the at least one bump has an aspect ratio of from about 0.1 to 1.0.

Claim 33 (New): The method of claim 31,
wherein the elastic resin of the elastic conductive resin composition is a silicone resin,
and
wherein the silicone resin comprises both an ultraviolet-curing property and a
humidity-curing property.

Claim 34 (New): A method of forming a connection part,
wherein the connection part comprises an elastic conductive element and a
metallic foil,
comprising
forming the elastic conductive element from the elastic conductive resin composition
of claim 1, and
attaching the elastic conductive element to the metallic foil to form the connection
part.

Claim 35 (New): A method of forming an electronic part,
wherein the electronic part comprises at least one electrode and a bump,
comprising
forming the bump from the elastic conductive resin composition of claim 1, and
attaching the bump to the at least one electrode to form the electronic part.

Claim 36 (New): A method of forming a bump on an electrode, comprising:
screen-printing a conductive paste comprising the elastic conductive resin
composition of claim 1 and a diluent on said electrode;
heat-curing the conductive paste at a temperature lower than a complete curing
temperature while evaporating the diluent; and

subsequently further heat-curing the conductive paste until a temperature of the conductive paste reaches the complete curing temperature,

wherein, in the elastic resin of the elastic conductive resin composition is a heat curing silicon resin.

Claim 37 (New): A method of forming a connection part comprising an elastic conductive element formed from the elastic conductive resin composition of claim 1, and a metallic foil provided onto the elastic conductive element, comprising:

coating a metallic foil with the elastic conductive resin composition at a predetermined thickness;

curing the elastic conductive resin composition; and

cutting the cured elastic conductive resin composition and the metallic foil.